



RECOMMENDED P.C.B HOLE LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)

- 1.MATERIAL:
- 1.1 INSULATOR & COVER: PBT WITH 30% GF, UL94V-0
INSULATOR & COVER COLOR: BLUE (661C)
 - 1.2 CONTACT: BRASS
 - 1.3 SHIELD: SPCC
 - 1.4 RIVET: BRASS
 - 1.5 BOARDLOCK: SPCC
 - 1.6 SCREW: STEEL
 - 1.7 BRACKET: PA66 WITH 30% GF, UL94V-0,
COLOR: BLUE(661C)

- 2.FINISH:
- 2.1 CONTACT: SELECTIVE GOLD PLATED (SEE ORDER INFORMATION) IN CONTACT AREA, 100μ" MIN. MATTE TIN PLATED IN SOLDER AREA 50μ" MIN.NICKEL UNDERPLATED OVERALL.
 - 2.2 SHIELD: 50μ" MIN. NICKEL PLATED OVERALL.
 - 2.3 RIVET: 50μ" MIN. NICKEL PLATED OVERALL.
 - 2.4 BOARDLOCK: 100μ" MIN. TIN PLATED IN SOLDER AREA 50μ" MIN.NICKEL UNDERPLATED OVERALL.
 - 2.5 SCREW: 50μ" MIN. NICKEL PLATED OVERALL.

- 3.ELECTRICAL CHARACTERISTICS
- 3.1 CURRENT RATING: 3.0 A.
 - 3.2 CONTACT RESISTANCE: 30mΩ MAX.
 - 3.3 INSULATION RESISTANCE: 1000MΩ MIN.
 - 3.4 DIELECTRIC WITHSTANDING VOLTAGE: AC 1000V PER MINUTE.
 - 3.5 OPERATING TEMPERATURE: -55°C ~ +105°C.

- 4.NOTES:
- 4.1 THIS COMPONENT AND ITS HOMOGENEOUS SUBCOMPONENTS ARE RoHS COMPLIANT.
 - 4.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 5 SECONDS, AND ONLY FOR WAVE SOLDERING PROCESS.

5. ORDER INFORMATION:
- DB31 X Z X AH X SX -15D
- SCREW:
1: WITH SCREW ASSEMBLED
3: W/O SCREW
- CONTACT PLATED:
S1: GOLD FLASH
S2: 3u" GOLD
S3: 5u" GOLD
S4: 10u" GOLD
S5: 15u" GOLD
S6: 30u" GOLD
- CONTACT MATERIAL:
1: BRASS
2: PHOSPHOR BRONZE

SCREW HEIGHT:
D: 5.80mm
N: W/O

REV.	DESCRIPTION	ECN NO.	NAME	DATE
A0	NEW RELEASE		Milo	Oct.30.2013

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE: ±3°	

TITLE: D-SUB 15 PINS FEMALE HIGH RAISE R/A DIP TYPE				
DWG. NO.: C-DB31XZXAHXSX-15D			DRAWN: Milo	
PART NO.: DB31XZXAHXSX-15D			CHECKED: David	
UNIT: mm	SCALE: none	SHEET: 1 OF 1	DWG. SIZE: A4	LAYER: CN280
APPROVED: Peter			RFQ NO.:	

RFQ NO.:
Q1308078&Q1308079

REVISIONS